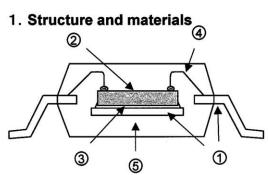


# Package: TQFPXXV

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Structure and materials	1/4 page
2. Tape and Reel information	1/4 to 3/4 page
3. Storage conditions	3/4 page
4. Marking lot number	3/4 page
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6 Soldering conditions	3/4 to 4/4 page



F:-	4	Structure
FIG.		Situciure

No.	Item	Materials
1	Lead Frame	Cu-Alloy (External lead : Pb free solder plating)
2	Die	Silicon
3	Die Attach	Ag Paste
4	Wire	Au
⑤	Molding	Epoxy Resin

### 2. Tape and Reel information

#### 2. 1. Packing specification

Таре	Embossed carrier tape(with dry pack)			
Quantity	See the table on page 4/4			
Direction of feed	E2 (See Fig. 2)			

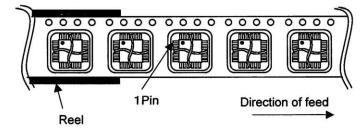


Fig. 4 Reel dimensions

#### 2. 2. Tape and Reel specification

2. 2. 1. Tape and reel dimensions ( See the table on page 4/4 )

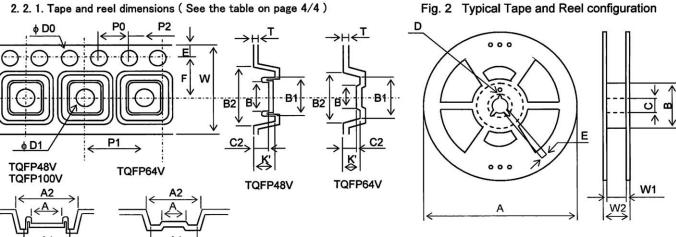


Fig. 3 Tape dimensions

#### 2. 3. Leader and Trailer

#### 2. 3. 1. Leader

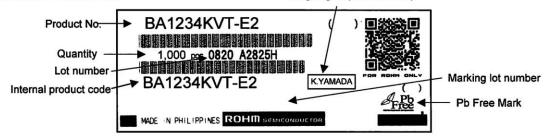
No component pockets are 40 pockets or more.

#### 2. 3. 2. Trailer

No component pockets are 10 pockets or more. Tape is free from reel.

#### 2. 4. Label for Reel and Box

#### Out going inspection stamp



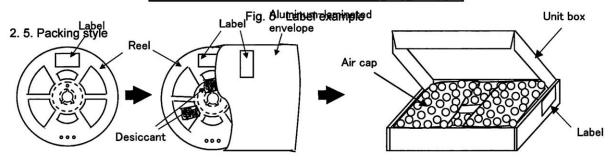
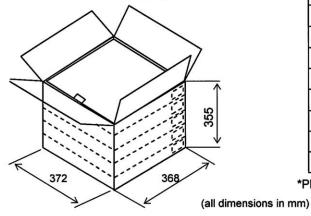


Fig. 6 Packing style

#### 2. 6. Shipping style

5 unit boxes or less per shipping box



#### 2. 7. Packing materials

Item	Material			
Embossed carrier tape	PS			
Cover tape	PET + PE			
Reel	PS			
Desiccant	Silicagel			
Envelope	Aluminume-laminated			
Air cap	Polyethylene			
Unit box	Cardboard			
Shipping box	Cardboard			

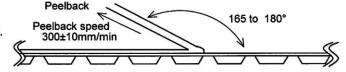
<sup>\*</sup>Please obey the indication of top side in a shipping box.

Fig. 7 Shipping box dimensions and Shipping style

#### 2. 8. Others

#### 2. 8. 1. Peelback strength

Cover tape peelback strength is 0.2 to 0.7N.



#### 2. 8. 2. Missing Ics

- (1) No consecutive dropouts.
- (2) A maximun 0.1% of specified number of products in each packing may be missing.

#### 3. Storage conditions

#### 3. 1. Storage environment

Recommended storage conditions are as follows:

-Temperature : 5 to 30°C -Humidity : 40 to 70% RH

#### 3. 2. Storage period

-Specified storage period: 1 year

#### 3.3. Specified storage period until soldering

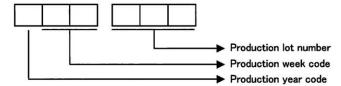
After dry pack is opened, assemble package within 168hours.

If the storage period has expired, the products must be baked 125°C for 24hours.

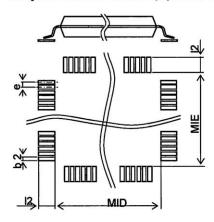
Maximum 2times baking for keeping solderbility.

Execute baking by 60°C/48hours while put in the embossed tape.

#### 4. Marking lot number



#### 5. Footprint dimensions (Optimize footprint dimensions to the board design and soldering condition)

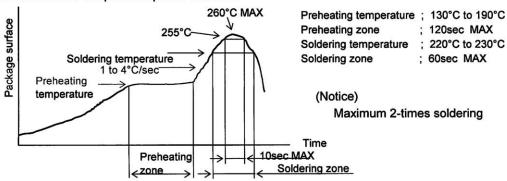


(all	dimensions	in mm)	
(all	Ullicialona		

Dookogo	Land pitch	Land	space	Land length	Land width
Package	е	MID	MIE	≥ 12	b2
TQFP48V	0.50	7.20	7.20	1.20	0.25
TQFP64V	0.50	10.20	10.20	1.20	0.25
TQFP100V	0.50	14.20	14.20	1.20	0.25

#### 6. Soldering conditions

#### 6. 1. Recommended temperature profile for reflow



#### 6. 2. Recommended condition for wave soldering

Process	Conditions					
Process	Temperature	Time				
Preheating	120°C to 150°C	60sec MAX				
Soldering	260°C ± 3°C	12sec MAX				

(Notice) Soldering time is provided for total soldering time in case of dual wave soldering.

#### 6. 2. 1. Notes for wave soldering

- (1) Do not use other soldering methods with wave soldering.
- (2) Recommend to clean the board to eliminate flux, solder waste, and other impurities for reliability, after soldering.
- (3) Optimize soldering condition to prevent solder bridging.

#### 6. 3. Recommended condition for solder iron

Recommended condition for solder iron
-Solder iron temperature : 380°C or less
-Mounting time : 4sec or less

#### < Tape dimensions >

Package	Quantity		Tape dimensions (all dimensions in mm)									
Package	(pcs)	Α	A1	A2	В	B1	B2	C2	D0	D1	E	F
TQFP48V	1500	6.95	(7.75)	9.9	6.95	(7.75)	9.9	(1.15)	φ1.5	ф1.6	1.75	7.5
TQFP64V	1000	9.0	12.5	(12.65)	9.0	12.5	(12.65)	1.2	φ1.5	φ1.5	1.75	11.5
TQFP100V	500	13.73	14.63	17.0	13.73	14.63	17.0	(1.3)	φ1.5	φ2.0	1.75	11.5
Tolera	nce		±0.1	1	-	±0.1	_	±0.1	+0.1 -0	+0.1 -0	±0.1	±0.1

	Tape dimensions (all dimensions in mm)								
Package	K'	P0	P1	P2	Т	W			
TQFP48V	1.6	4.0	12.0	2.0	0.3	16.0			
TQFP64V	(1.7)	4.0	16.0	2.0	0.3	24.0			
TQFP100V	1.6	4.0	24.0	2.0	0.3	16.0			
Tolerance	T -	±0.1	±0.1	±0.1	±0.05	±0.3			

#### < Reel dimensions >

Destros	Reel dimensions (all dimensions in mm)						
Package	Α	В	С	D	E	W1	W2
TQFP48V	ф330	ф80	φ13.0	ф20.2	1.5	17.5	22.5
TQFP64V	ф330	φ100	φ13.0	φ20.2	1.5	25.5	30.5
TQFP100V	ф330	φ100	φ13.0	ф20.2	1.5	25.5	30.5
Tolerance	-	-	±0.2	MIN	MIN	±1.0	MAX

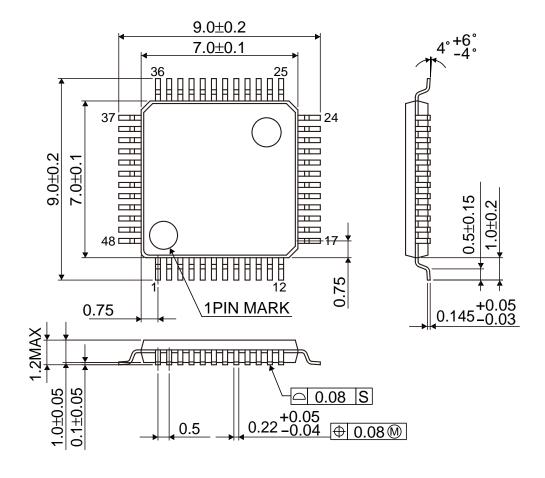
#### < Dehydrated weight >

Dehydrated weigh dimensions in g
0.15
0.27
0.52



# Package Dimensions

## **TQFP48V**

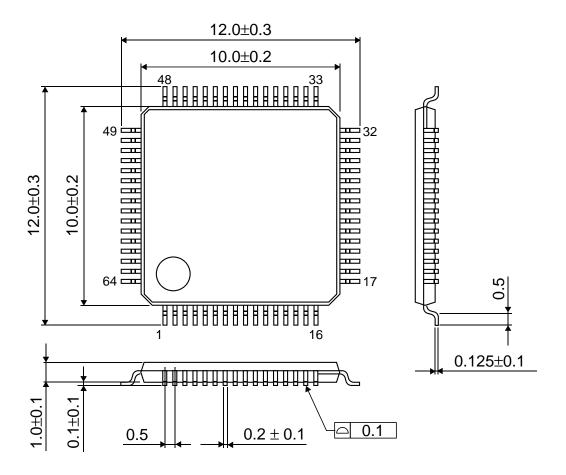


(Unit: mm)



# Package Dimensions

## TQFP64V

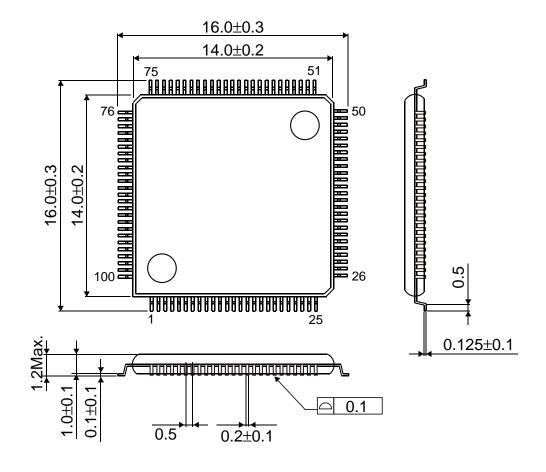


(Unit: mm)



# **Package Dimensions**

## TQFP100V



(Unit: mm)

#### Notes

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